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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: SHYH-CHYI KUO, ET AL.)
Application Serial No.: 10/622,892) Attorney Docket No.: IT0090-US
Filed: July 16, 2003)
Title: METHOD FOR FABRICATING A)
HOLLOW MICRO-NEEDLE ARRAY)

SUBMISSION OF REVOCATION OF POWER OF ATTORNEY
AND GRANT OF POWER OF ATTORNEY

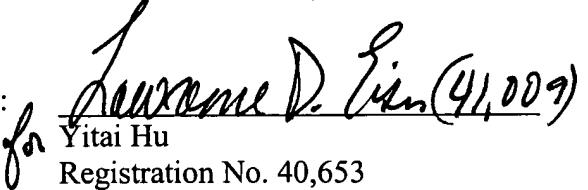
Assistant Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicants hereby submit the attached Revocation of Power of Attorney and Grant of Power of Attorney in the above-identified application. Should there be any questions with respect to this submission a representative of the Patent Office is requested to contact the undersigned.

Respectfully submitted,

SHYH-CHYI KUO, ET AL.

Date: November 18, 2004
By: 
for Lawrence D. Lin (41,009)
Yitai Hu
Registration No. 40,653

SHAW PITTMAN LLP
1650 Tysons Boulevard
McLean, VA 22102-4859
703-770-7900

YH/LDE/lrhj

Customer No. 28970



PATENT
Customer No. 28970

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Patent Application and Patent Numbers: **See attached "Schedule A"**

REVOCATION OF POWER OF ATTORNEY
AND GRANT OF NEW POWER OF ATTORNEY

The undersigned, a representative authorized to sign on behalf of the assignee owning all of the interest in the listed and pending patent applications and issued patents on the attached sheet (Schedule A), hereby revokes all previous powers of attorney or authorization of agent granted in these patents before the date of execution hereof. The undersigned verifies that **INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE** is the assignee of the entire right, title, and interest in each of the pending patent applications and issued patents listed on the attached Schedule A and is identified as the assignee by assignments from the inventor(s) in the listed pending patent applications and issued patents as filed accordingly at the U.S. Patent and Trademark Office. The undersigned certifies that the evidentiary documents have been reviewed and to the best of the undersigned's knowledge and belief, title in each of the pending patent applications and issued patents listed on the attached Schedule A is in the assignee **INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE**.



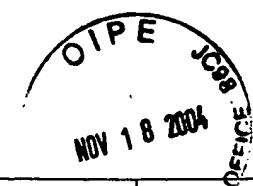
By the undersigned's signature, **INDUSTRIAL TECHNOLOGY RESEARCH INSTITUTE** hereby grants power of attorney for each of the pending patent applications and issued patents listed on the attached Schedule A to **SHAW PITTMAN LLP**, Michael D. Bednarek, Reg. No. 32,329; Lawrence J. Gotts, Reg. No. 31,163; Aslan Baghdadi, Reg. No. 34,542; Yitai Hu, Reg. No. 40,653; Elizabeth M. Roesel, Reg. No. 34,878; David C. Isaacson, Reg. No. 38,500; Steven P. Arnheim, Reg. No. 43,475; Poh C. Chua, Reg. No. 44,615; Michael A. Oblon, Reg. No. 42,956; Lawrence D. Eisen, Reg. No. 41,009; Mark Koehn, Reg. No. 46,271; Michelle S. Marks, Reg. No. 41,971; Brett C. Martin, Reg. No. 52,000; Chad D. Wells, Reg. No. 50,875; Tara L. Hutchings, Reg. No. 46,559; John Kasha, Reg. No. 53,100; Ann P. McGeehan, Reg. No. 45,839; June E. Cohan, Reg. No. 43,741; and Joanne Kim, Reg. No. 51,193, both jointly and separately as its attorneys with full power of substitution and revocation, to transact all business in the Patent and Trademark Office connected with each of the pending patent applications and issued patents listed on the attached Schedule A.

Please send all future correspondence concerning the pending patent applications and issued patents listed on the attached Schedule A to **SHAW PITTMAN LLP** at the following address:

Shaw Pittman LLP
1650 Tysons Blvd.
McLean, Virginia 22102

Dated: Sept. 9, 2004

By: Benjamin Wang
(name) Benjamin Wang
(title) Deputy General Director
Industrial Technology Research Institute



SCHEDULE A

| SERIAL NUMBER | FILING DATE | TITLE | PATENT NUMBER | ISSUE DATE |
|---------------|----------------|--|---------------|-------------------|
| 10/714,277 | Nov. 14, 2003 | Conductive Bumps with Non-Conductive Juxtaposed Sidewalls and Method for Fabricating | N/A | N/A |
| 09/596,181 | June 16, 2000 | Method for Fabricating Electron Emitter Stacks for Field Emission Display Panel and Structures Formed | N/A | N/A |
| 10/656,755 | Sept. 6, 2003 | Thermal Bubble Membrane Microfluidic Actuator | N/A | N/A |
| 10/427,449 | April 30, 2003 | Flexible Electronic/Optical Interconnection Film Assembly and Method for Manufacturing | N/A | N/A |
| 10,622,892 | July 16, 2003 | Method for Fabricating a Hollow Micro-Needle Array | N/A | N/A |
| 10/863,700 | June 7, 2004 | Buried Array Capacitor and Microelectronic Structure Incorporating the Same | N/A | N/A |
| 10/833,713 | April 27, 2004 | Image Sensor Packaging Structure and Method | N/A | N/A |
| 08/670,505 | June 27, 1996 | Thin Film Transistor Liquid Crystal Display Device Having Multi-Layer Optical Film as Light Shield and Method of Manufacturing | N/A | N/A |
| 10/057,026 | Jan. 24, 2002 | Integrated Inkjet Print Head with Rapid Ink Refill Mechanism and Off-Shooter Heater | N/A | N/A |
| 10/654,314 | Sept. 3, 2003 | Microfluidic Component Providing Multi-Directional Fluid Movement | N/A | N/A |
| 09/130,698 | Aug. 7, 1998 | Ball Grid Array Package Equipped with Cooling System | N/A | N/A |
| 10/653,860 | Sept. 3, 2003 | Self-Assembled Nanometer Conductive Bumps and Method for Fabricating | N/A | N/A |
| 09/273,691 | March 22, 1999 | Front-Side Repairable TFT-LCD and Method for Making | 6,714,269 | March 30, 2004 |
| 10/197,321 | July 16, 2002 | Micro Liquid Dispenser Incorporating a Liquid Pillar Injector and Method for Operating | 6,663,214 | December 16, 2003 |
| 10/345,861 | Jan. 15, 2003 | Three-Dimensional Stacked Heat Spreader Assembly for Electronic Package and Method for Assembling | 6,700,783 | March 2, 2004 |
| 10/689,262 | Oct. 20, 2003 | Integrated Probe Module for LCD Panel Light Inspection | N/A | N/A |



SCHEDULE A

| SERIAL NUMBER | FILING DATE | TITLE | PATENT NUMBER | ISSUE DATE |
|---------------|----------------|---|---------------|-------------------|
| 10/713,804 | Nov. 14, 2003 | Embedded Microelectronic Capacitor Incorporating Ground Shielding Layers and Method for Fabrication | N/A | N/A |
| 09/991,723 | Nov. 23, 2001 | Method for Bonding Inner Leads to Bond Pads Without Bumps and Structures Formed | 6,656,772 | December 2, 2003 |
| 10/079,748 | Feb. 19, 2002 | Method for Forming Cantilever Beam Probe Card and Probe Card Formed | 6,651,325 | November 25, 2003 |
| 10,345,861 | Jan. 15, 2003 | Three-Dimensional Stacked Heat Spreader Assembly for Electronic Package and Method for Assembling | 6,700,783 | March 2, 2004 |
| 09,273,691 | March 22, 1999 | Front-Side Repairable TFT-LCD and Method for Making | 6,714,269 | March 30, 2004 |
| 08/947,381 | Oct. 8, 1997 | Method for Forming Metal Silicide by Laser Irradiation | 6,316,357 | November 13, 2001 |
| 09/273,023 | March 19, 1999 | Planar Fluorescent Lamp with Flat Electrodes and Method for Fabricating | 6,639,351 | October 28, 2003 |

Customer No. 28970